

NOTES:

MAT'L

HOUSING: LCP

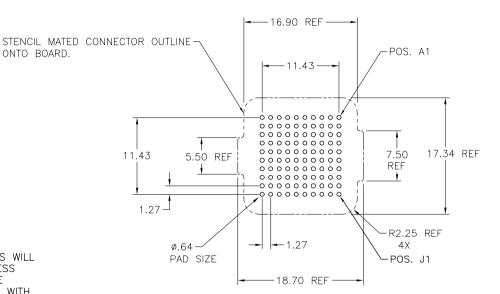
CONTACT: COPPER ALLOY

**PLATING** 

CONTACT: (SEE TABLE ON SHEET1) SOLDER BALL: (SEE TABLE ON SHEET1) EUTECTIC SnPb OR LEAD FREE

95.5Sn/4Aa/0.5Cu

- 2. OVERALL BOARD-TO-BOARD STACK HEIGHT WHEN MATED TO P/N 84512 100 POSITION 0mm RECPT. IS 4.0mm REF.
- 3. PLATING FOR -2XX SERIES DASH NOS. MEETS THE REQUIREMENTS OF NORTEL NPS25298-2 (CENTRAL OFFICE ENVIRONMENT, 25 YEAR LIFE EXPECTANCY).
- (4.) FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THERFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION
- (5.) THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION



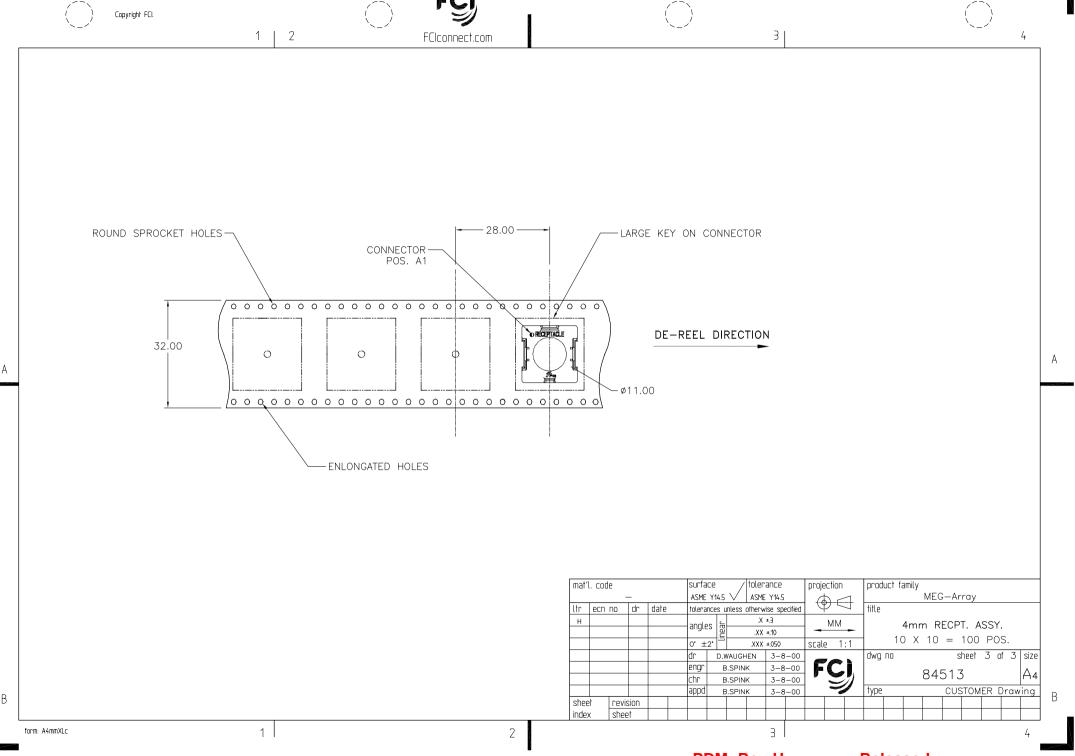
BOARD PATTERN

mat'l. code							surface /			tolerance		projection		product family									
	ASME Y14.5 ✓			ASME Y14.5		<b>⊕</b> ←		MEG-Array															
ltr	ecn no dr date					tolera	nces i	ınless	otherw	rwise specified		W		title									
Н						angles E			E.± X.			MM			4mm RECPT. ASSY.								
						0° ±2°			.XXX ±.050			scale	2 1	:1	10 X 10 = 100 POS.								
								VAUGH	HEN	3-8	3-8-00				dwg	no			S	heet	2 0	of 3	size
								B.SPINK		3-8-00		FC		. Î			84513					A4	
						chr		B.SPINK		3-8-00											H4		
						appd	B.SPIN		K 3-8-00		-00			type			CUSTOMER Draw				ring		
sheet		revision																					
index	x	sheet																					
										3													4

form: A4mmXLc

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PDM: Rev:H



PDM: Rev:H STATE

STATUS: Released